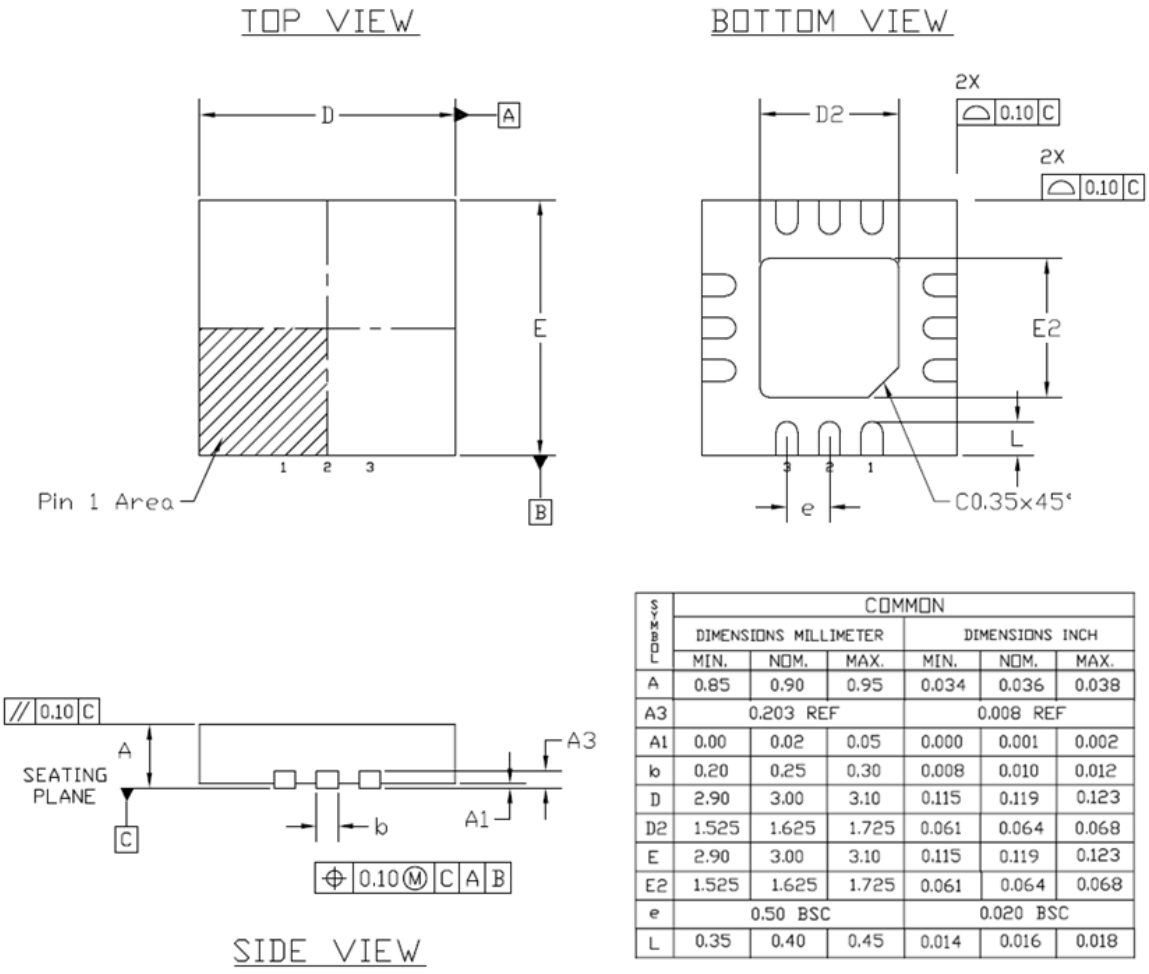
Package Outline Dimension

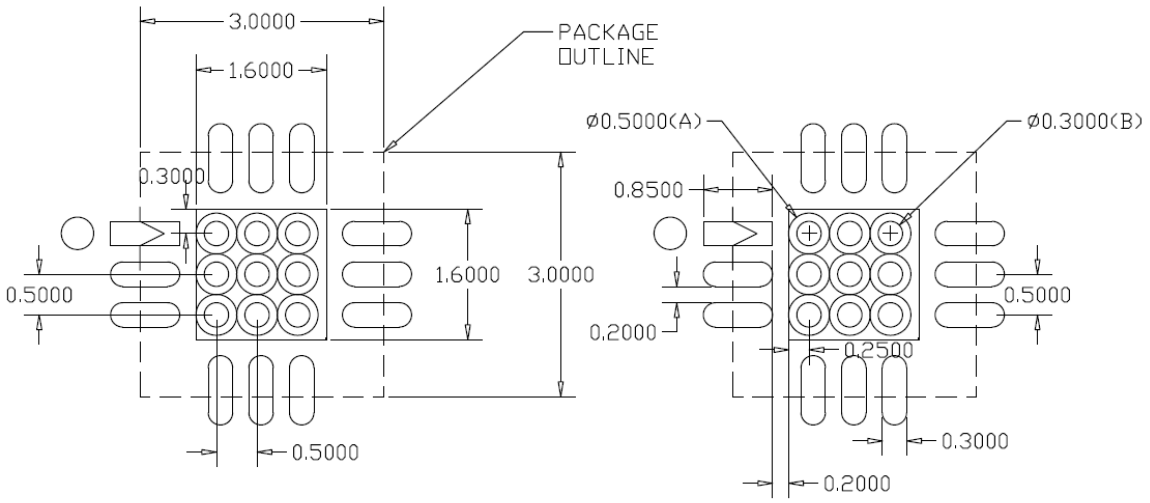


SYMBOL	COMMON					
	DIMENSIONS MILLIMETER			DIMENSIONS INCH		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.85	0.90	0.95	0.034	0.036	0.038
A3	0.203 REF			0.008 REF		
A1	0.00	0.02	0.05	0.000	0.001	0.002
b	0.20	0.25	0.30	0.008	0.010	0.012
D	2.90	3.00	3.10	0.115	0.119	0.123
D2	1.525	1.625	1.725	0.061	0.064	0.068
E	2.90	3.00	3.10	0.115	0.119	0.123
E2	1.525	1.625	1.725	0.061	0.064	0.068
e	0.50 BSC			0.020 BSC		
L	0.35	0.40	0.45	0.014	0.016	0.018

NOTES :

1. DIMENSION AND TOLERANCING CONFORM TO ASME Y14.5M-1994.
2. CONTROLLING DIMENSIONS : MILLIMETER. CONVERTED INCH DIMENSION ARE NOT NECESSARILY EXACT.
3. DIMENSION b APPLIES TO METALLIZED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM. FROM TERMINAL TIP.
4. INSULATION THICKNESS, CLEARANCE OF OVERLAP ARE USER DEFINED.
5. INSULATION NOT COMPLETELY SHOWN FOR REASONS OF CLARITY.

Suggested PCB Land Pattern and PAD Layout

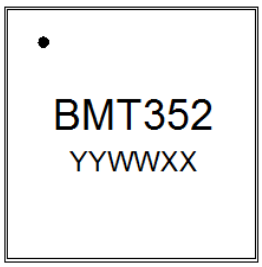


Unit : mm

• Notes

1. Use 1 oz. copper minimum for top and bottom layer metal.
2. A heatsink underneath the area of the PCB for the mounted device is required for proper thermal operation.
3. Ground / thermal vias are critical for the proper performance of this device.

Package Marking



YY = Year, WW = Working Week,
XX = Wafer No.